



BZT52HC18WFQ

SURFACE MOUNT ZENER DIODE

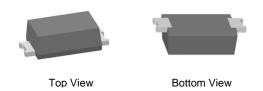
Features

- Flat Lead Package Design for Low Profile and High Power Dissipation
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

- Case: SOD123F
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish Matte Tin Annealed over Copper Alloy Leadframe. Solderable per MIL-STD-202, Method 208 @3)
- Polarity: Cathode Band
- Weight: 0.015 grams (Approximate)

SOD123F (Type B)



Ordering Information (Note 5)

	Part Number	Compliance	Case	Packaging
	BZT52HC18WFQ-7	Automotive	SOD123F (Type B)	3000/Tape & Reel
Notes:	1. No purposely added lead.	Fully EU Directive 2002/95/EC (RoHS), 20	11/65/EU (RoHS 2) & 2015/863/EU (RoHS	3) compliant.

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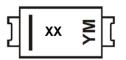
2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to https://www.diodes.com/quality/.

5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



XX = Product Type Marking Code (See Electrical Characteristics Table) YM = Date Code Marking Y = Year (ex: G = 2019) M = Month (ex: 9 = September)

Date Code Ke	әу											
Year	2018	2019	2020	202	1 2	2022		2025	202	6 2	2027	2028
Code	F	G	Н	-		J		М	N		0	Р
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Forward Voltage (Note 6)	@ I _F = 10mA	VF	0.9	V
Forward Current		lF	250	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 7)	PD	375	mW
Power Dissipation (Note 8)	PD	830	mW
Thermal Resistance, Junction to Ambient Air (Note 7)	$R_{ ext{ heta}JA}$	330	°C/W
Thermal Resistance, Junction to Ambient Air (Note 8)	R _{0JA}	150	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-65 to +150	°C

Notes:

Short duration pulse test used to minimize self-heating effect.
Device mounted on FR-4 PCB with minimum recommended pad layout, as shown in Diodes Incorporated's Suggested Pad Layout document, which can be found on our website at http://www.diodes.com/package-outlines.html.
Device mounted on FR-4 PCB with mounting pad for cathode 1cm².

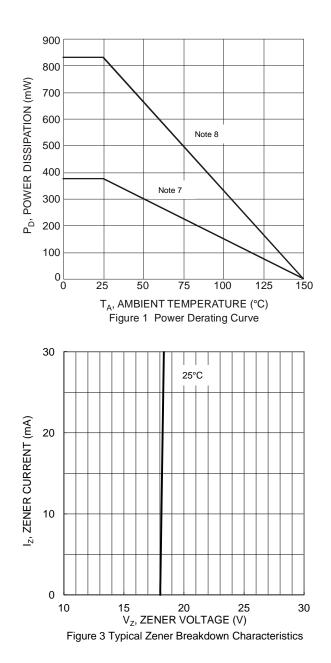


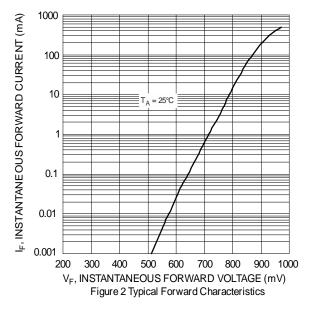
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

	Marking Codes	Zener Voltage Range (Note 9)		Maximu	ximum Zener Impedance (Note 10) Temperature Coefficient				Total Capacitance	Maximum Reverse Current (Note 9)			
Type Number		•		Vz @ Izt Izt		Z _{ZK} @ I _{ZK}	I _{ZK}	T _C @ I _{ZT}		C _T @ f = 1MHz, V _R = 0V	I _R	I _R @V _R	
		Min (V)	Max (V)	mA	2	2	mA	Min (mV/°C)	Max (mV/°C)	Max (pF)	μA	v	
BZT52HC18WFQ	WL	16.8	19.1	5	20	170	1	12.4	16.0	70	0.05	12.6	

Notes:

9. Short duration pulse test used to minimize self-heating effect. 10. f = 1 kHz.



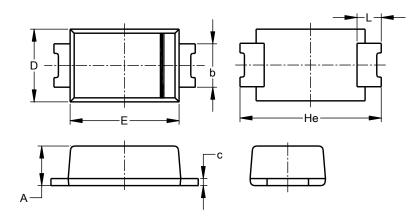




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

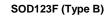
SOD123F (Type B)

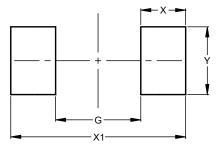


SOD123F (Type B)								
Dim	Min	Max	Тур					
Α	0.81	1.15						
b	0.80	1.35						
С	0.05	0.30						
D	1.70	1.90	1.80					
Е	2.60	2.80	2.70					
He	3.30	3.70	3.50					
L	0.35	0.85						
All	Dimen	sions	in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.





Dimensions	Value (in mm)
G	1.90
Х	1.00
X1	3.90
Y	1.50



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